

表面安装桥式整流器

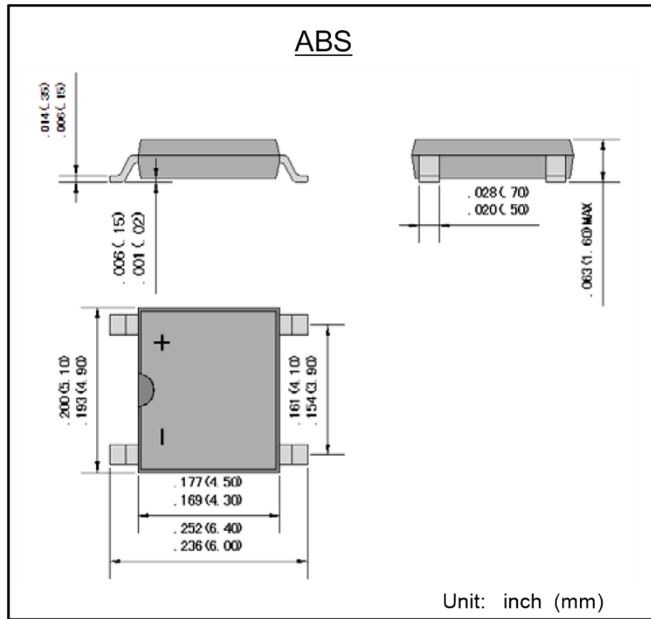
反向电压 1000 V

正向电流 1.6 A

Surface Mount Bridge-Rectifiers

Reverse Voltage 1000 V

Forward Current 1.6 A



特征 Features

- 玻璃钝化芯片 Glass passivated chip
- 反向漏电流低 Low reverse leakage
- 正向浪涌承受能力强 High forward surge capability
- 高温焊接保证 High temperature soldering guaranteed:
260°C/10 秒 260°C/10seconds
- 引线 and 管体皆符合RoHS标准。
Lead and body according with RoHS standard

机械数据 Mechanical Data

- 封装: ABS 塑封 Case: ABS Molded plastic
- 极性: 标记模压或印于本体
Polarity: Symbols molded or marked on body
- 安装位置: 任意 Mounting Position: Any

最大值和特性 TA = 25°C 除非另有规定。

Maximum Ratings & Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

参数 Parameter	符号 Symbols	ABS210	单位 Unit
最大可重复峰值反向电压 Maximum repetitive peak reverse voltage	V_{RRM}	1000	V
最大均方根电压 Maximum RMS voltage	V_{RMS}	700	V
最大直流阻断电压 Maximum DC blocking voltage	V_{DC}	1000	V
最大正向平均整流电流 Maximum average forward rectified current 在环氧树脂玻璃P.C.B板上 On glass-epoxy P.C.B 在铝基板上 On aluminum substrate	$I_{F(AV)}$	1.6 2.0	A
正向不重复浪涌电流8.3 ms单一正弦半波 Non-repetitive peak forward surge current 8.3 ms single half sine-wave	I_{FSM}	50	A
最大正向电压 @ $I_F=0.8A$ Maximum forward voltage	V_F	0.95	V
最大反向电流 @ V_{DC} TA= 25°C Maximum reverse current	I_R	10	μA
典型热阻 Typical thermal resistance (Note 1)	RθJA	80	°C/W
工作结温和存储温度 Operating junction and storage temperature rang	Tj, TSTG	-55 --- +150	°C

备注 Note:

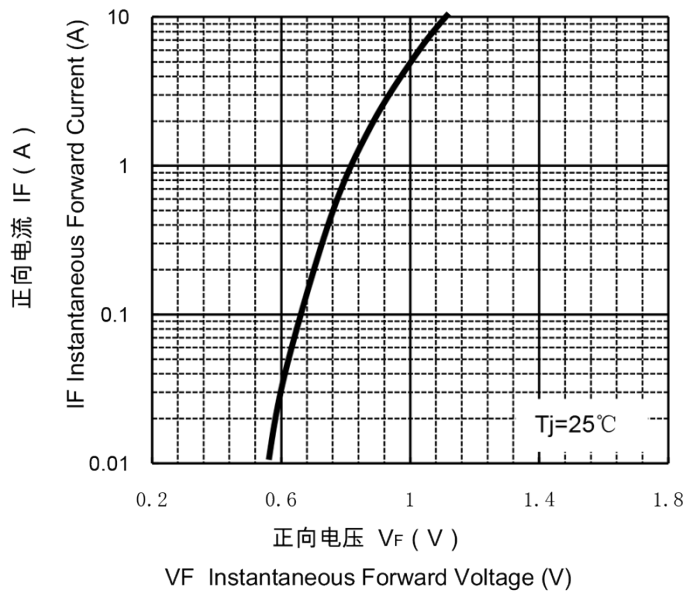
1) 安装在PCB板上，从PN结到环境的热阻。

1) Thermal resistance from junction to ambient , PCB mounted.

特性曲线 Characteristic Curves

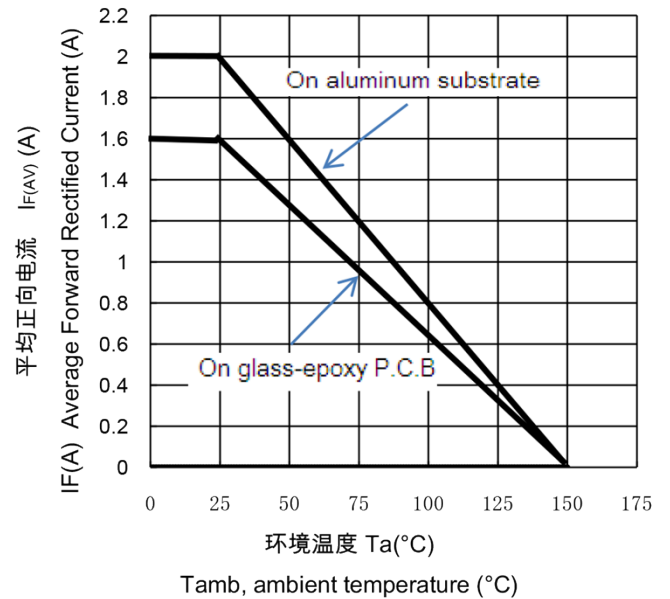
正向特性曲线 (典型值)

TYPICAL FORWARD CHARACTERISTIC



正向电流降额曲线

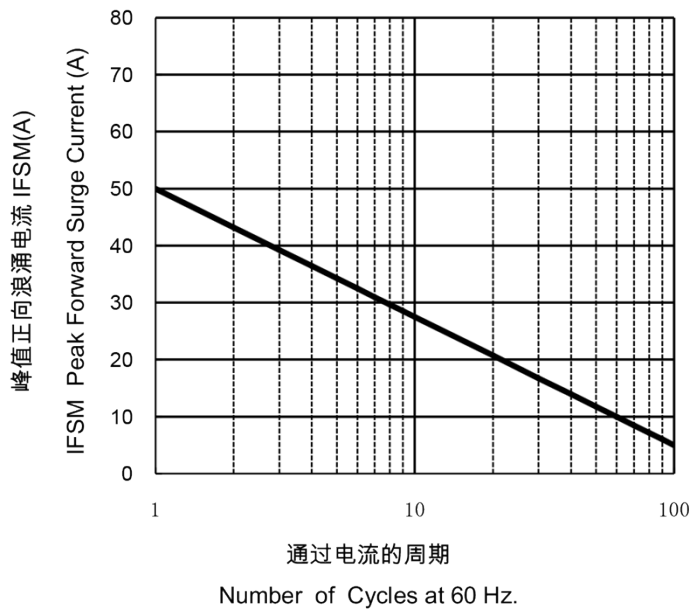
FORWARD CURRENT DERATING CURVE



浪涌特性曲线 (最大值)

MAXIMUM NON REPETITIVE

PEAK FORWARD SURGE CURRENT



反向特性曲线

Typical Reverse Characteristics

